CategoryTOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)/Category

# SSM6K08FU

#### **High Speed Switching Applications**

Unit: mm

• Small package

• Low on resistance:  $R_{on} = 105 \text{ m}\Omega \text{ (max) (@V_{GS} = 4 V)}$ 

 $R_{on} = 140 \text{ m}\Omega \text{ (max) (@VGS} = 2.5 \text{ V)}$ 

• High-speed switching:  $t_{on} = 16 \text{ ns (typ.)}$ 

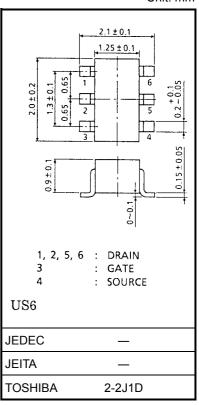
 $t_{off} = 15 \text{ ns (typ.)}$ 

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	20	V	
Gate-Source voltage		V <sub>GSS</sub>	±12	V	
Drain current	DC	I <sub>D</sub>	1.6	А	
	Pulse	I <sub>DP</sub>	3.2		
Drain power dissipation		P <sub>D</sub> (Note1)	300	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

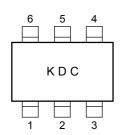
Note1: Mounted on FR4 board.

(25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 0.32 mm<sup>2</sup>  $\times$  6) Figure 1.

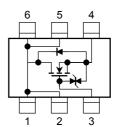


Weight: 6.8 mg (typ.)

#### Marking Circuit (top view)



## **Equivalent**



#### **Handling Precaution**

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

#### **Electrical Characteristics (Ta = 25°C)**

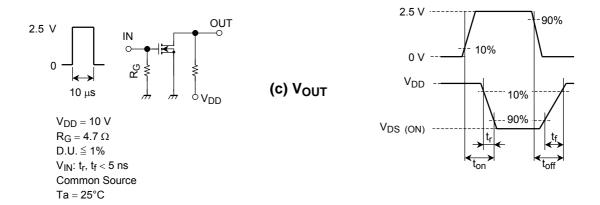
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$	_	_	±1	μА	
Drain Course breekdown voltage		V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$	20	_	_	V	
Drain-Source breakdown voltage	V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -12 \text{ V}$	12	_	_	v		
Drain cut-off curre	ent	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0$	_	_	1	μА	
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.5	_	1.2	V	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 3 \text{ V}, I_D = 0.8 \text{ A}$ (Note2)	2.0	_	_	S	
Drain-Source ON resistance		R <sub>DS</sub> (ON)	$I_D = 0.8 \text{ A}, V_{GS} = 4 \text{ V}$ (Note2)	_	77	105	mΩ	
			$I_D = 0.8 \text{ A}, V_{GS} = 2.5 \text{ V}$ (Note2)	_	100	140		
			$I_D = 0.8 \text{ A}, V_{GS} = 2.0 \text{ V}$ (Note2)	_	125	210		
Input capacitance	•	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz	_	306	_	pF	
Reverse transfer	transfer capacitance $C_{rss}$ $V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	44	_	pF		
Output capacitance		Coss	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz	_	74	_	pF	
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 10 \text{ V}, I_D = 0.8 \text{ A},$	_	16	_	ns	
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0~2.5 \text{ V}, R_G = 4.7 \Omega$	_	15	_		

Note2: Pulse test

#### **Switching Time Test Circuit**



#### (b) V<sub>IN</sub>



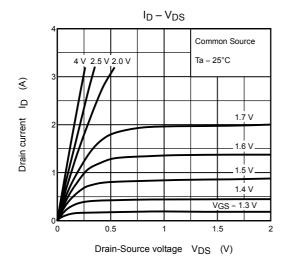
#### **Precaution**

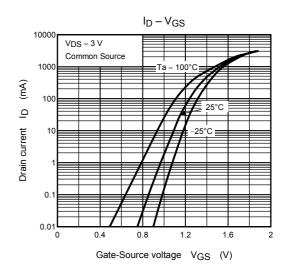
 $V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = 100~\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires lower voltage than  $V_{th}$ .

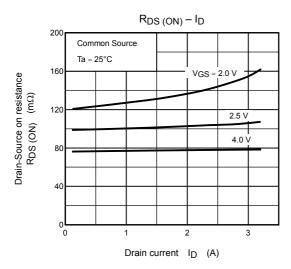
(Relationship can be established as follows:  $V_{GS\ (off)}$  <  $V_{th}$  <  $V_{GS\ (on)}$  )

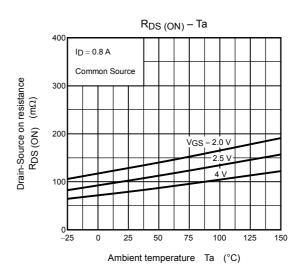
Please take this into consideration for using the device.  $V_{GS}$  recommended voltage of 2.5~V or higher to turn on this product.

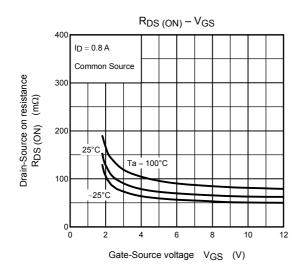
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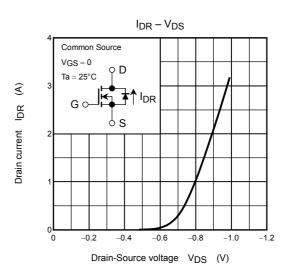




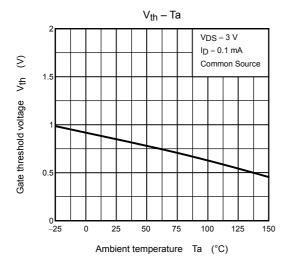


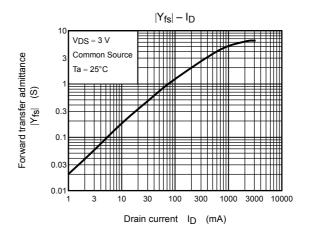


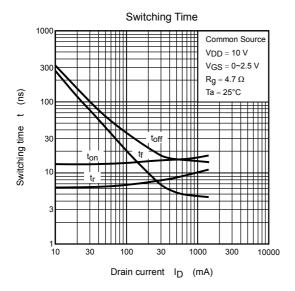


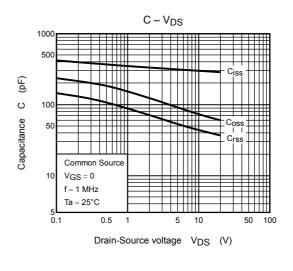


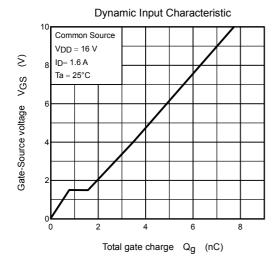
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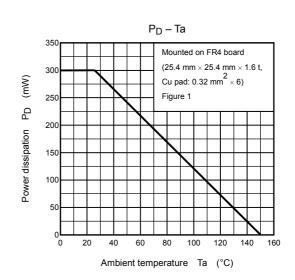


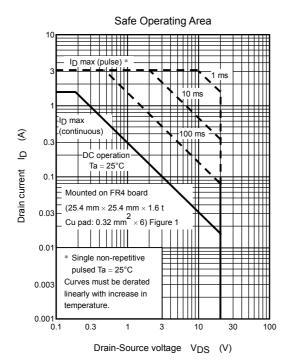


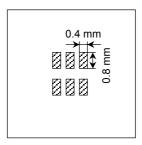












25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 0.32 mm  $^2 \times 6$ 

Figure 1

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### RESTRICTIONS ON PRODUCT USE

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